



**PRINTED CIRCUIT BOARDS**  
**INTERCONNECTION CARRIERS**

State of the Art: PCB's

Revisio

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**01**

**4.11.2001**

**1/1**

**Schematic Key for Multilayer and HDI-Technology Build-Ups**

a	b	c	d	e	f	g + h + i
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**04 154 FR4 100 L41.105 P18**

columns and equal kind of positions are separated by "\_". Equal prefixes in one column are reduced to one.

**04\_154\_FR4\_100\_L41.105\_p18**

Layers	in $\mu$	Material	Build-Up	Assembly
<b>Layer-1</b>	100 $\mu$	Copper		A1 B
	180 $\mu$	Prepreg		
	180 $\mu$	Prepreg		
<b>Layer-2</b>	105 $\mu$	Copper		
	410 $\mu$	L-FR4		
<b>Layer-3</b>	105 $\mu$	Copper		
	180 $\mu$	Prepreg		
	180 $\mu$	Prepreg		
<b>Layer-99</b>	100 $\mu$	Copper		

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